



SOT1052-2

HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

15 February 2022

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON8
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-01-2022
Manufacturer package code	98ASA01831D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3	-	mm
package width	-	2	-	mm
seated height	-	0.5	-	mm



HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

2 Package outline

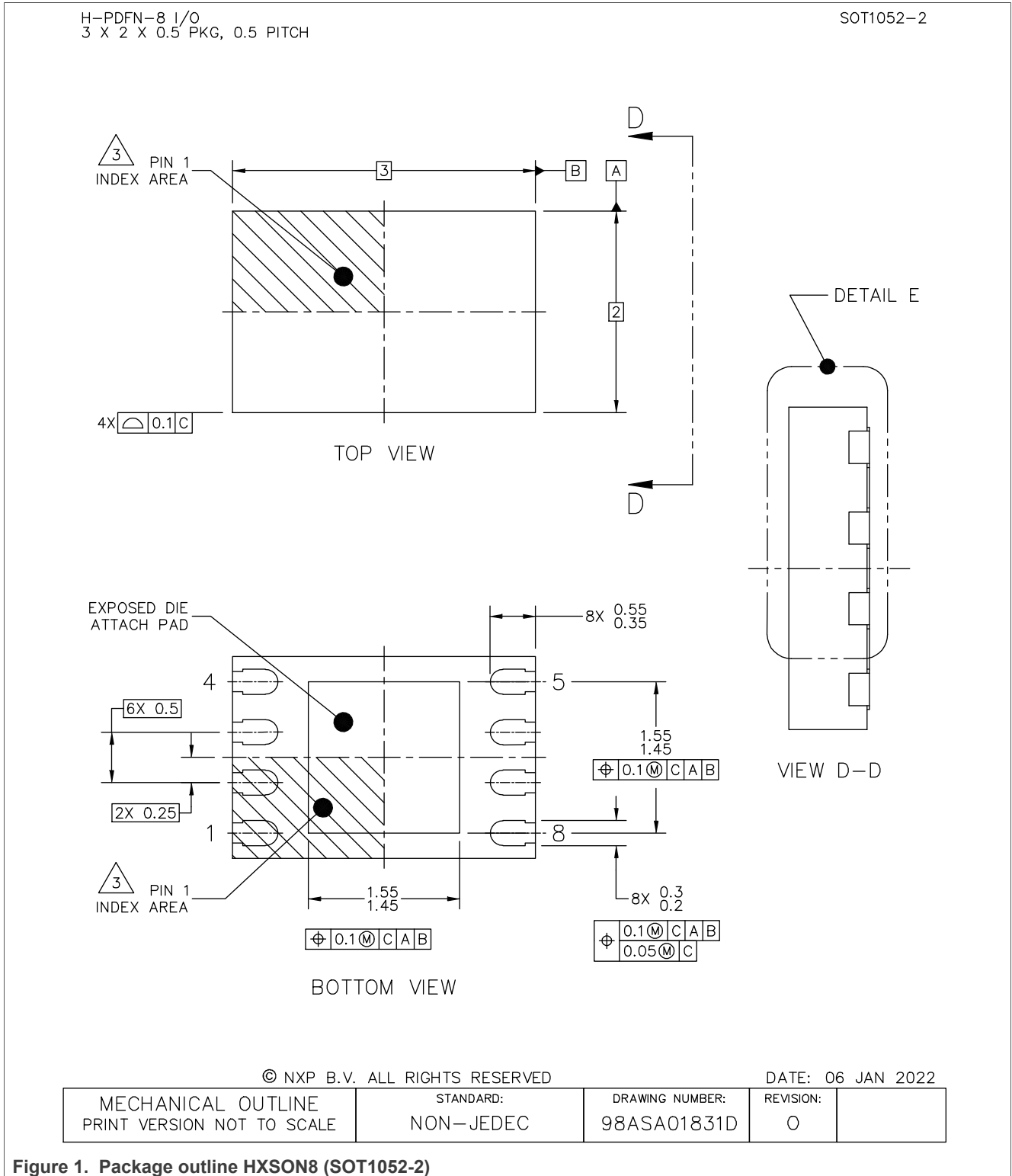
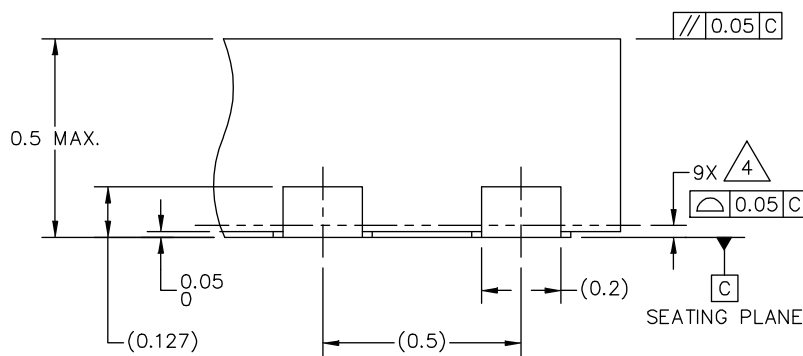


Figure 1. Package outline HXSON8 (SOT1052-2)

HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

H-PDFN-8 I/O
3 X 2 X 0.5 PKG, 0.5 PITCH

SOT1052-2



DETAIL E
VIEW ROTATED 90° CW

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DATE: 06 JAN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01831D	REVISION: O	
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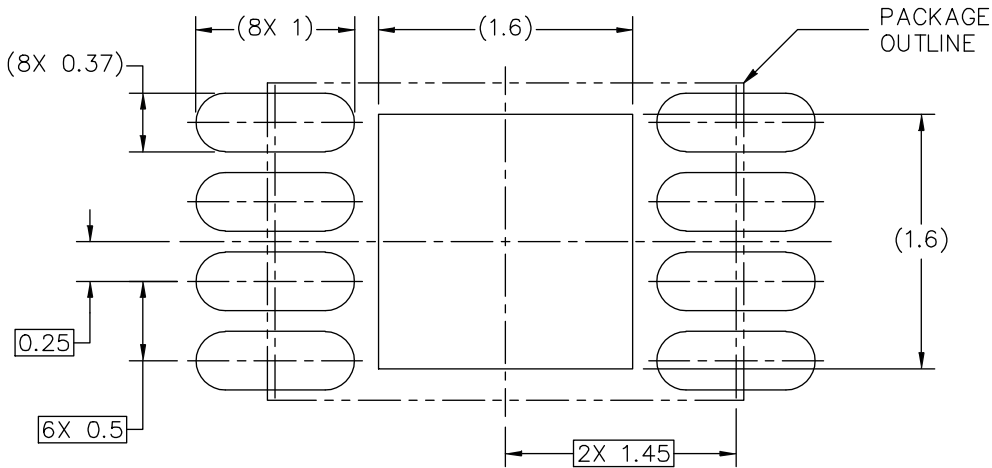
Figure 2. Package outline detail E of HXSON8 (SOT1052-2)

HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

3 Soldering

H-PDFN-8 I/O
3 X 2 X 0.5 PKG, 0.5 PITCH

SOT1052-2



PCB DESIGN GUIDELINES
RECOMMENDED SOLDER MASK OPENING PATTERN

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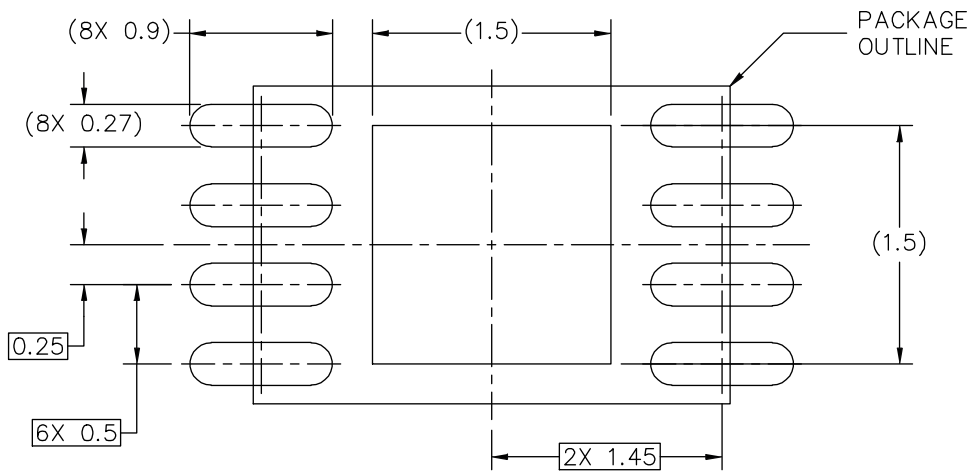
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01831D	REVISION: 0
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Figure 3. Reflow soldering footprint part1 for HXSON8 (SOT1052-2)

HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

H-PDFN-8 I/O
3 X 2 X 0.5 PKG, 0.5 PITCH

SOT1052-2



PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

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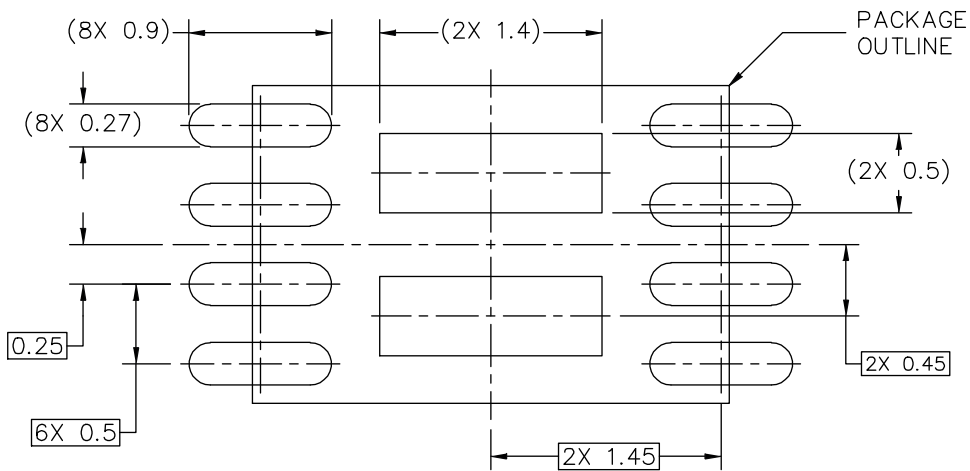
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01831D	REVISION: 0	
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Figure 4. Reflow soldering footprint part2 for HXSON8 (SOT1052-2)

HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

H-PDFN-8 I/O
3 X 2 X 0.5 PKG, 0.5 PITCH

SOT1052-2



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – RECOMMENDED SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HXSON8 (SOT1052-2)

HXSON8: thermal enhanced extremely thin small outline package; no leads; 8 terminals, 0.5 mm pitch, 3 mm x 2 mm x 0.5 mm body

H-PDFN-8 I/O
3 X 2 X 0.5 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HXSON8 (SOT1052-2)

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4 Legal information

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